

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number PZU16B2A-Q Part Description										
									Nexperia DHAM			
									SMD package			
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST									
			Pre- and Post-Stress									
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
ı		JESD22-A113										
	DC	Bake Tamb = 125 °C	24 hours									
# A1	PC Preconditioning	Soak Tamb = 85 °C, RH = 85% Reflow soldering	168 hours 3 cycles	1514	64430	0						
# AI	Treconditioning	MIL-STD-750-1	5 Cycles	1314	04430	0						
	HTRB	M1038 Method A										
		Tj = Tjmax, VR = 80 % of rated reverse										
# B1	Bias	voltage	1000 hours	250	11400	0						
		MIL-STD-750-1										
		M1038 Method B										
	SSOP	Tj = Tjmax, $Iz = 100%$ of max. datasheet										
# B1b	Steady State Operational	reverse current	1000 hours	44	1920	0						
	TC	JESD22-A104				_						
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0						
	UHAST	JESD22-A118										
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %										
" 7.5 C.	Olibiased Fixes	JESD22-A102	- 96 hours	311	14080	0						
	AC	Tamb = 121 °C, RH = 100 %										
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)										
	H3TRB	JESD22-A101										
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^[1]	1000 hours	311	14080	0						
		MIL-STD-750 Method 1037										
	IOL	ton = toff, devices powered to insure ΔTj =										
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	312	14120	0						
		JECD22 4444										
# 60	RSH Resistance to Solder Heat	JESD22-A111	10 -	260	0070	0						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0						
# C10	SD Solderability	1-STD-002		10	6660	0						
# C10	Solderability	J-STD-002	4450	19	6660	0						

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11400	0	0,37	2,68E+09

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com